



#### 40V +175°C N-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

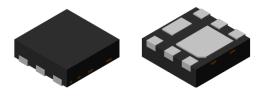
BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
40) /	11.5m $\Omega$ @ V <sub>GS</sub> = 10V	11.6A
40V	$18m\Omega @ V_{GS} = 4.5V$	9.3A

### **Description**

This new generation MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) and yet maintain superior switching performance, making it ideal for high efficiency power management applications:

- Power Management Functions
- DC-DC Converters
- Backlighting

#### U-DFN2020-6 (SWP) (Type F)



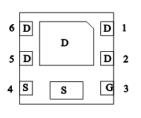
Top View Bottom View

### **Features**

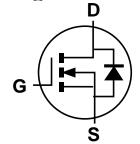
- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching, Test in Production Ensures More Reliable and Robust End Application
- Low R<sub>DS(ON)</sub> Ensures On State Losses Are Minimized
- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm<sup>2</sup>
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (<u>DMTH4008LFDFWQ</u>)

#### **Mechanical Data**

- Case: U-DFN2020-6 (SWP) (Type F)
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe;
  Solderable per MIL-STD-202, Method 208 (23)
- Weight: 0.007 grams (Approximate)







Internal Schematic

### Ordering Information (Note 4)

Part Number	Case	Quantity Per Reel
DMTH4008LFDFW-7	U-DFN2020-6 (SWP) (Type F)	3,000
DMTH4008LFDFW-13	U-DFN2020-6 (SWP) (Type F)	10,000

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

# **Marking Information**



8W = Product Type Marking Code YM = Date Code Marking Y = Year (ex: F = 2018) M = Month (ex: 9 = September)

Date Code Key

Year	201	7	2018	201	9	2020	202	1	2022	2023	3	2024
Code	Е		F	G		Н			J	K		L
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage		$V_{DSS}$	40	V
Gate-Source Voltage	$V_{GSS}$	±20	V	
Continuous Drain Current (Note 7) V <sub>GS</sub> = 10V	D	11.6 8.2	Α	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	80	Α	
Continuous Source-Drain Diode Current (Note 7)	Is	2.55	Α	
Pulsed Source-Drain Diode Current (10µs Pulse, Duty Cycle = 1%)	I <sub>SM</sub>	80	Α	
Avalanche Current, L = 0.3mH (Note 8)	I <sub>AS</sub>	14.7	Α	
Avalanche Energy, L = 0.3mH (Note 8)	E <sub>AS</sub>	32.4	mJ	

# **Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	$P_{D}$	0.99	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	153	°C/W
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	P <sub>D</sub>	2.35	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	64.5	°C/W
Thermal Resistance, Junction to Case (Note 7)	T <sub>C</sub> = +25°C	R <sub>0</sub> JC	14.8	°C/W
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to +175	°C

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition				
OFF CHARACTERISTICS (Note 9)										
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	40		_	V	$V_{GS} = 0V, I_D = 250\mu A$				
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 32V, V_{GS} = 0V$				
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$				
ON CHARACTERISTICS (Note 9)	· · · · · · · · · · · · · · · · · · ·									
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1	1.7	3	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$				
Static Drain-Source On-Resistance	Б		9.1	11.5	mΩ	$V_{GS} = 10V, I_D = 10A$				
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	12.9	18	11122	$V_{GS} = 4.5V, I_D = 8.5A$				
Diode Forward Voltage	$V_{SD}$	_	0.8	1.0	V	$V_{GS} = 0V, I_{S} = 10A$				
DYNAMIC CHARACTERISTICS (Note 10)										
Input Capacitance	C <sub>iss</sub>	_	1030	_						
Output Capacitance	Coss	_	324	_	pF	$V_{DS} = 20V, V_{GS} = 0V,$ f = 1MHz				
Reverse Transfer Capacitance	C <sub>rss</sub>	_	27	_		I = IIVIMZ				
Gate Resistance	Rg	_	1.82	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$				
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	6.8	_						
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	14.2	_	nC	V 20V I 40A				
Gate-Source Charge	Q <sub>gs</sub>	_	2.0	_	IIC	$V_{DD} = 20V, I_D = 10A$				
Gate-Drain Charge	Q <sub>gd</sub>	_	2.7	_						
Turn-On Delay Time	t <sub>D(ON)</sub>	_	3.1	_						
Turn-On Rise Time	t <sub>R</sub>	_	3.1	_		$V_{DD} = 20V, V_{GS} = 10V,$				
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	14.2	_	ns	$R_g = 6\Omega$ , $I_D = 10A$				
Turn-Off Fall Time	t <sub>F</sub>	_	5.8	_		-				
Reverse Recovery Time	t <sub>RR</sub>	_	19.6	_	ns	1 100 11/11 1000/				
Reverse Recovery Charge	Q <sub>RR</sub>	_	8.2	_	nC	I <sub>F</sub> = 10A, di/dt = 100A/μs				

Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

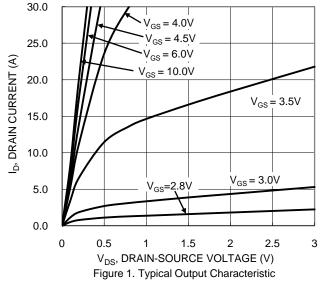
<sup>7.</sup> Thermal resistance from junction to soldering point (on the exposed drain pad). 8. I<sub>AS</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep T<sub>J</sub> =+ 25°C.

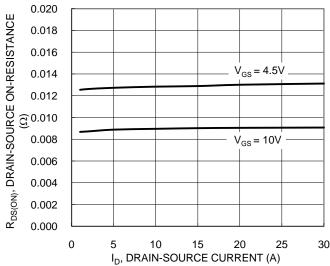
<sup>9.</sup> Short duration pulse test used to minimize self-heating effect.

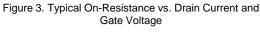
<sup>10.</sup> Guaranteed by design. Not subject to product testing.











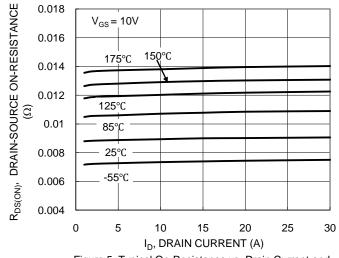
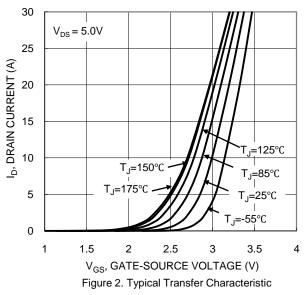
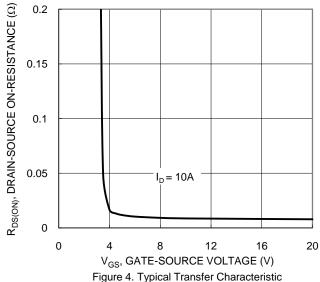


Figure 5. Typical On-Resistance vs. Drain Current and Temperature





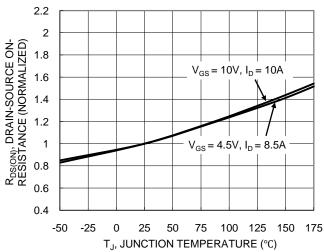


Figure 6. On-Resistance Variation with Temperature





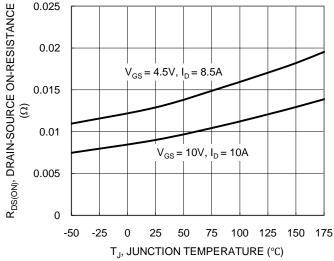
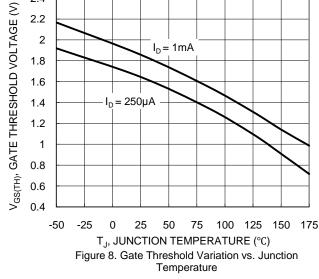


Figure 7. On-Resistance Variation with Temperature



2.4

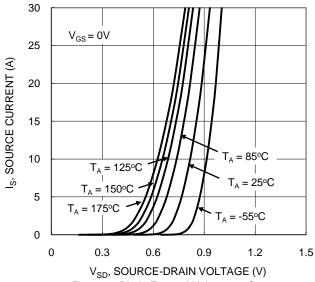
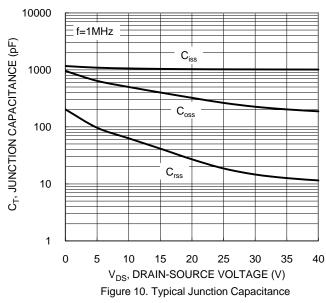


Figure 9. Diode Forward Voltage vs. Current



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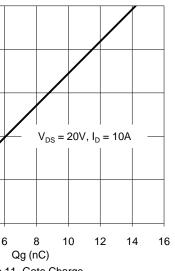
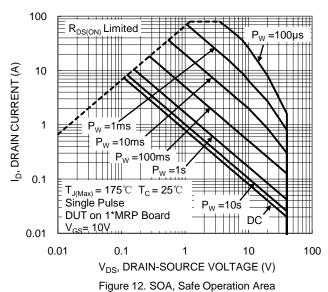


Figure 11. Gate Charge



10

8

4

2

0

0

2

 $V_{GS}(V)$ 



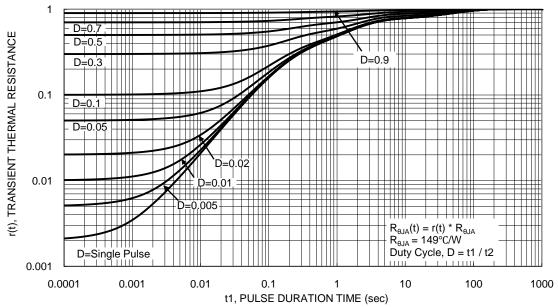


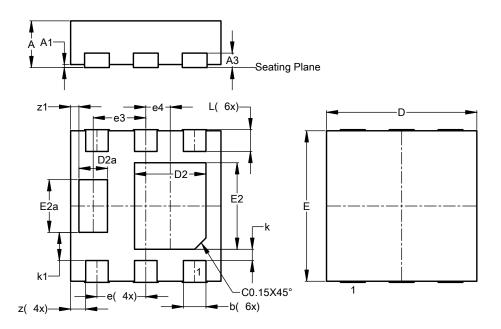
Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

# U-DFN2020-6 (SWP) (Type F)

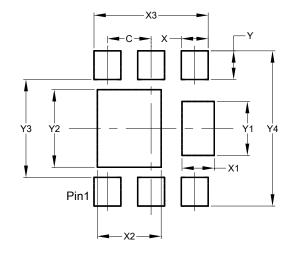


U-DFN2020-6 (SWP) (Type F)						
Dim	Min Max Typ					
Α	0.59	0.65	0.62			
A1	0.00	0.05	0.03			
A3	-	-	0.192			
b	0.28	0.38	0.33			
D	1.95	2.05	2.00			
D2	0.87	1.07	0.97			
D2a	0.35	0.45	0.40			
Е	1.95	2.05	2.00			
E2	1.07	1.27	1.17			
E2a	0.67	0.77	0.72			
е		0.65 B	SC			
е3		0.70 B	SC			
e4	C	).325 B	SC			
k			0.15			
k1			0.375			
L	0.225	0.355	0.305			
Z			0.20			
<b>z</b> 1			0.11			
All Dimensions in mm						

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### U-DFN2020-6 (SWP) (Type F)



Dimensions	Value (in mm)
С	0.650
X	0.400
X1	0.480
X2	0.950
Х3	1.700
Y	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300



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